Description

The series of devices uses **Super Trench II** technology that is uniquely optimized to provide the most efficient high frequency switching performance. Both conduction and switching power losses are minimized due to an extremely low combination of $R_{DS(ON)}$ and Q_g. This device is ideal for high-frequency switching and synchronous rectification.

Application

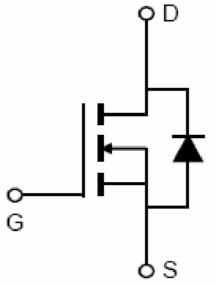
- DC/DC Converter
- Ideal for high-frequency switching and synchronous rectification

General Features

- V_{DS} =100V,I_D =160A
  $R_{DS(ON)}$=2.9mΩ , typical (TO-220)@ V_{GS}=10V
  $R_{DS(ON)}$=2.7mΩ , typical (TO-263)@ V_{GS}=10V
- Excellent gate charge x $R_{DS(on)}$ product(FOM)
- Very low on-resistance $R_{DS(on)}$
- 175 °C operating temperature
- Pb-free lead plating

TO-220C

TO-263



Schematic Diagram

Package Marking and Ordering Information

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
VST10N027-TC	VST10N027	TO-220C	-	-	-
VST10N027-T3	VST10N027	TO-263	-	-	-

Absolute Maximum Ratings (T_C=25℃unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	V_{DS}	100	V
Gate-Source Voltage	V_{GS}	±20	V
Drain Current-Continuous	I_D	160	A
Drain Current-Continuous(T_C=100℃)	I_D (100℃)	120	A
Pulsed Drain Current (Note 1)	I_{DM}	640	A
Maximum Power Dissipation	P_D	245	W
Derating factor		1.63	W/℃
Single pulse avalanche energy (Note 5)	E_{AS}	1345	mJ
Operating Junction and Storage Temperature Range	T_J,T_{STG}	-55 To 175	℃

Thermal Characteristic

Thermal Resistance,Junction-to-Case (Note 2)	$R_{\theta JC}$	0.61	℃/W
Thermal Resistance,Junction-to-Ambient (Note 2)	$R_{\theta JA}$	60	℃/W

Electrical Characteristics (T_C=25℃unless otherwise noted)

Parameter	Symbol	Condition	Min	Typ	Max	Unit
Off Characteristics						
Drain-Source Breakdown Voltage	BV_{DSS}	V_{GS}=0V I_D=250μA	100		-	V
Zero Gate Voltage Drain Current	I_{DSS}	V_{DS}=100V,V_{GS}=0V	-	-	1	μA
Gate-Body Leakage Current	I_{GSS}	V_{GS}=±20V,V_{DS}=0V	-	-	±100	nA
On Characteristics (Note 3)						
Gate Threshold Voltage	$V_{GS(th)}$	V_{DS}=V_{GS},I_D=250μA	2.0	3.0	4.0	V
Drain-Source On-State Resistance	$R_{DS(ON)}$	V_{GS}=10V, I_D=80A TO-220	-	2.9	3.3	mΩ
		TO-263		2.7	3.3	mΩ
Gate resistance	R_G		-	2.0	-	Ω
Forward Transconductance	g_{FS}	V_{DS}=5V,I_D=80A	85	-	-	S
Dynamic Characteristics (Note4)						
Input Capacitance	C_{iss}	V_{DS}=50V,V_{GS}=0V, F=1.0MHz	-	7810.5	-	PF
Output Capacitance	C_{oss}		-	887.3	-	PF
Reverse Transfer Capacitance	C_{rss}		-	30	-	PF
Switching Characteristics (Note 4)						
Turn-on Delay Time	$t_{d(on)}$	V_{DD}=50V,I_D=80A V_{GS}=10V,R_G=1.6Ω	-	25	-	nS
Turn-on Rise Time	t_r		-	15	-	nS
Turn-Off Delay Time	$t_{d(off)}$		-	52	-	nS
Turn-Off Fall Time	t_f		-	17	-	nS
Total Gate Charge	Q_g	V_{DS}=50V,I_D=80A, V_{GS}=10V	-	127.7	-	nC
Gate-Source Charge	Q_{gs}		-	41.8		nC
Gate-Drain Charge	Q_{gd}		-	35.5		nC
Drain-Source Diode Characteristics						
Diode Forward Voltage (Note 3)	V_{SD}	V_{GS}=0V,I_S=80A	-		1.2	V
Diode Forward Current (Note 2)	I_S		-	-	160	A
Reverse Recovery Time	t_{rr}	T_J = 25°C, I_F = 80A di/dt = 100A/μs(Note3)	-	74	-	nS
Reverse Recovery Charge	Qrr		-	164	-	nC

Notes:

1. Repetitive Rating: Pulse width limited by maximum junction temperature.
2. The value of $R_{\theta JA}$ is measured with the device mounted on 1in2 FR-4 board with 2oz. Copper, in a still air environment with T_A =25° C. The Power dissipation P_{DSM} is based on $R_{\theta JA}$ and the maximum allowed junction temperature of 150° C. The value in any given application depends on the user's specific board design, and the maximum temperature of 175° C may be used if the PCB allows it.
3. Pulse Test: Pulse Width ≤ 300μs, Duty Cycle ≤ 2%.
4. Guaranteed by design, not subject to production
5. EAS condition : Tj=25℃,V_{DD}=50V,V_G=10V,L=0.5mH,Rg=25Ω

Typical Electrical and Thermal Characteristics

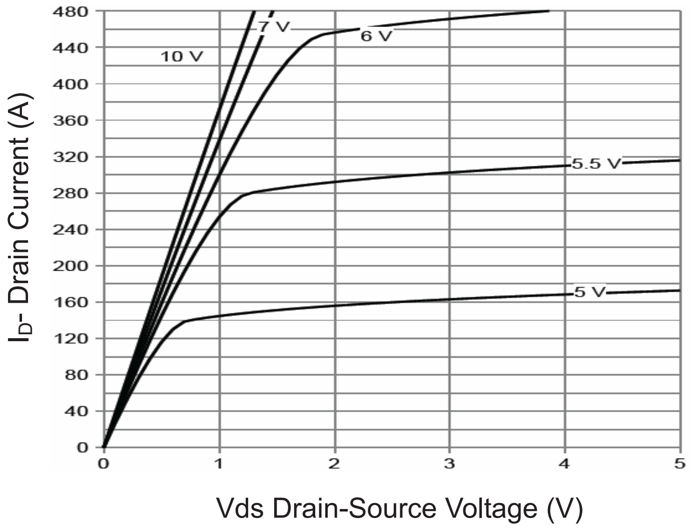


Figure 1 Output Characteristics

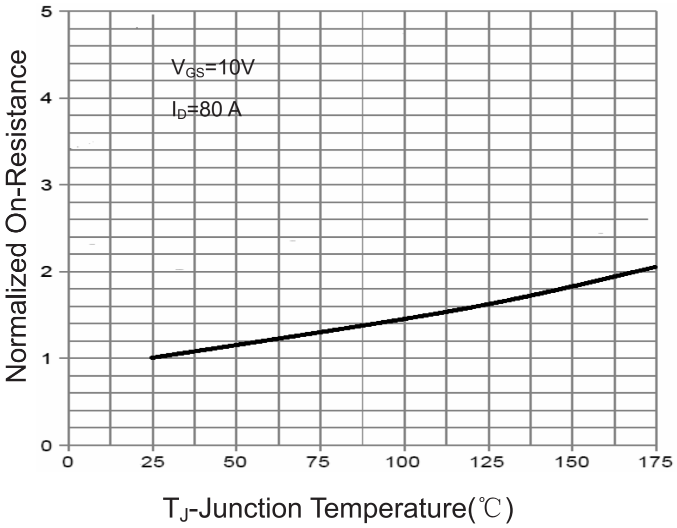


Figure 4 Rdson-Junction Temperature

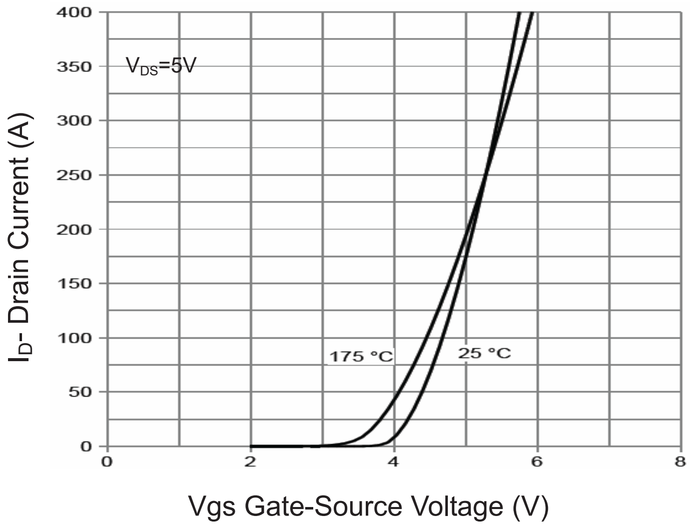


Figure 2 Transfer Characteristics

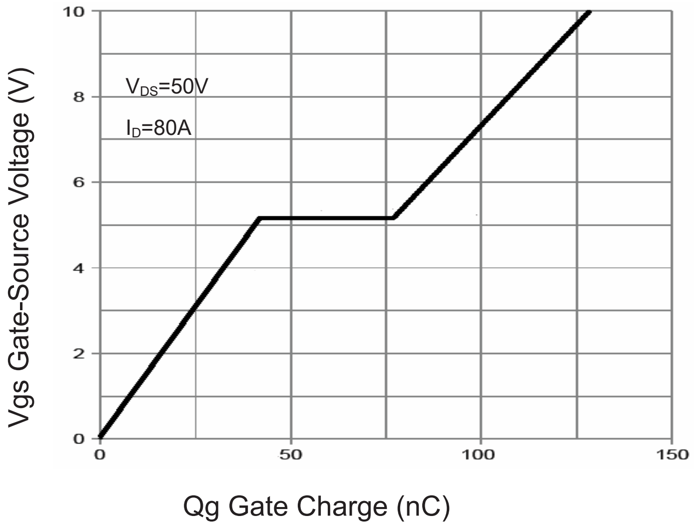


Figure 5 Gate Charge

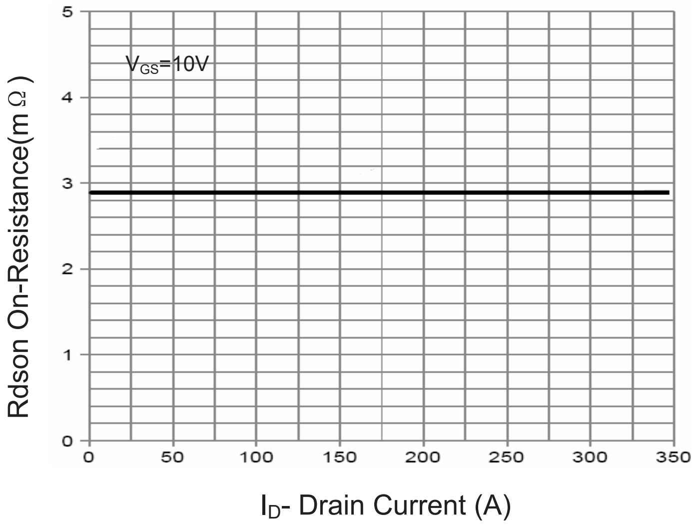


Figure 3 Rdson- Drain Current

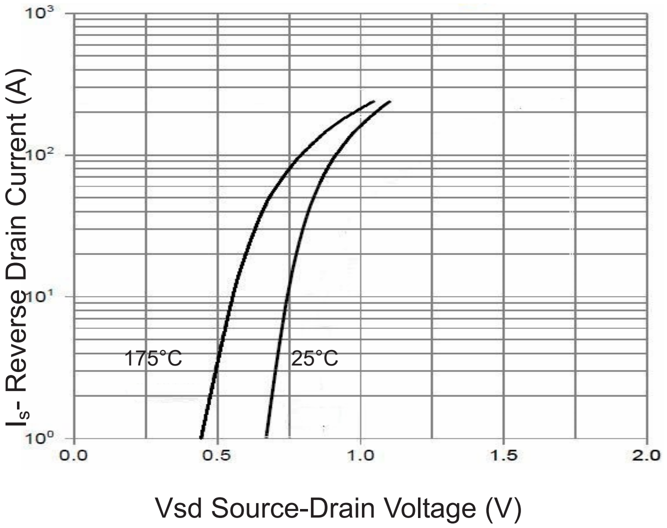


Figure 6 Source- Drain Diode Forward

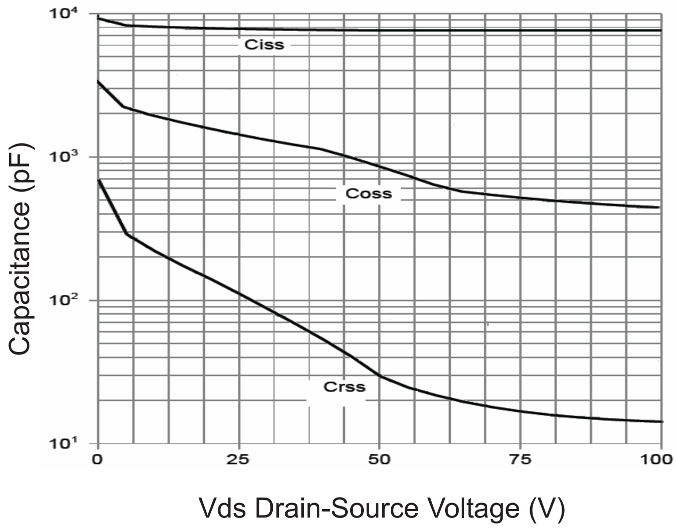


Figure 7 Capacitance vs Vds

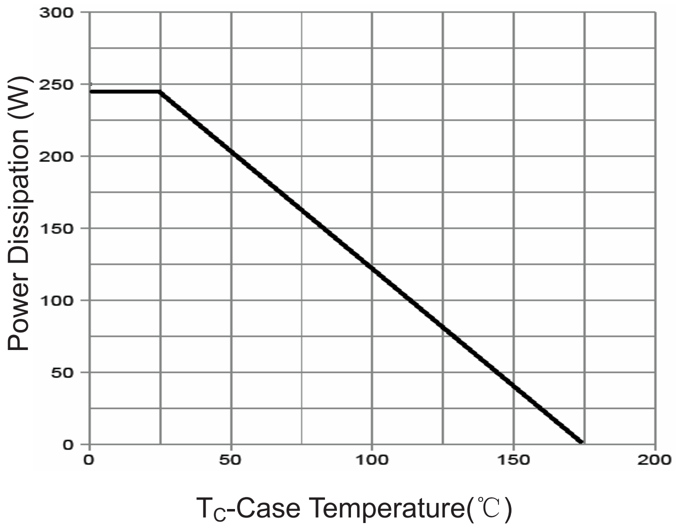


Figure 9 Power De-rating

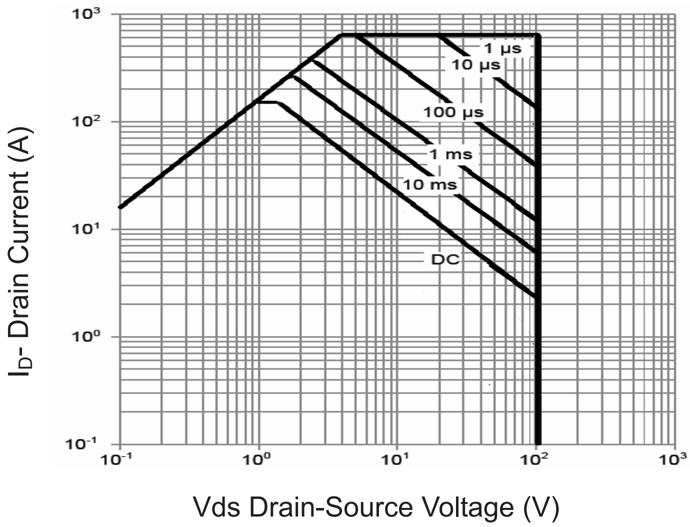


Figure 8 Safe Operation Area

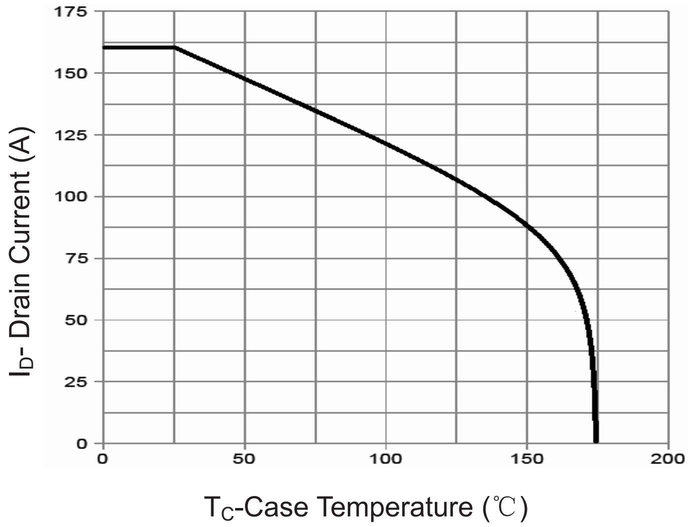


Figure 10 Current De-rating

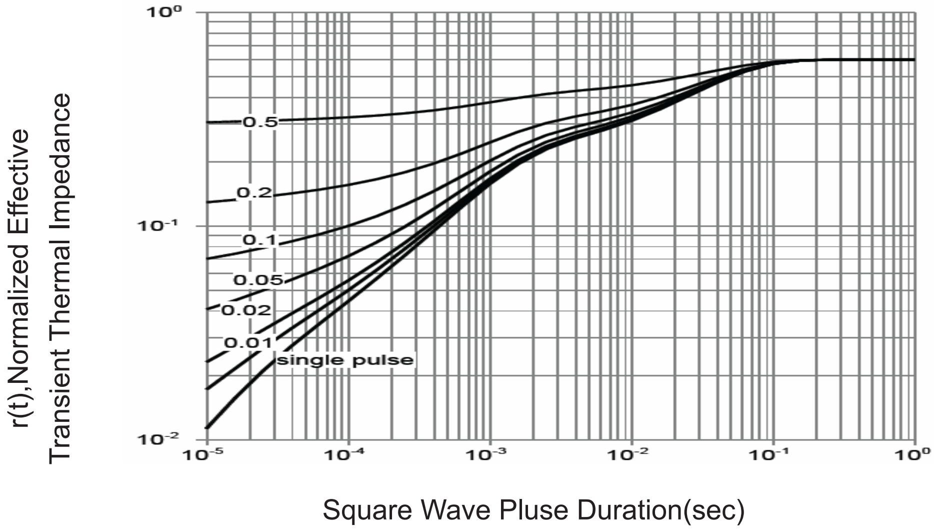


Figure 11 Normalized Maximum Transient Thermal Impedance